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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V.		PMEG100T150ELPE						
Name of Laboratory Assembly reliability labs		Part Description						
		Nexperia DHAM	Schottky					
		SMD package						
Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress							
# 1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
	PC	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours 168 hours					
# 2	Preconditioning	Reflow soldering	3 cycles	1514	64430	0		
# 5	HTRB High Temperature Reverse Bias	$\label{eq:milling} \begin{split} \text{MIL-STD-750-1} \\ \text{M1038 Method A} \\ \text{Tj} = \text{Tjmax}, \mbox{ Vr} = 100\% \mbox{ of max}. \mbox{ datasheet} \\ \text{reverse voltage}^{[1]} \end{split}$	1000 hours	206	9320	0		
		-				-		
# 7	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	500 cycles	311	14080	0		
# 8 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	— 96 hours	311	14080	0		
# 8a	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)						
# 9	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0		
# 10	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C	333 hours	312	14120	0		
# 20	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	269	8070	0		
# 20	SD	200 0 - 5 0	10.2	209	0070	U		
# 21	Solderability	J-STD-002		222	6660	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab T	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM S	Schottky	9320	0	0,46	2,19E+09

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